



<b>ABSOLUTE MAXIMUM RATINGS</b> $T_A = 25\text{ }^\circ\text{C}$ , unless otherwise noted			
Parameter	Symbol	Steady State	Unit
Logic Supply	$V_{DD}$	7	V
Logic Inputs	$V_{PWM}$	7.3	
Common Switch Node	$V_{SW}$	30	
Drain Voltage	$V_{IN}$	30	
Bootstrap Voltage	$C_{BOOT}$	SW + 7	
Maximum Power Dissipation (Measured at $25\text{ }^\circ\text{C}$ )	$P_D$	6	W
Operating Junction and Storage Temperature Range	$T_j, T_{stg}$	- 65 to 125	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature) <sup>a, b</sup>		225	

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating/conditions for extended periods may affect device reliability.

<b>RECOMMENDED OPERATING CONDITIONS</b>			
Parameter	Symbol	Steady State	Unit
Drain Voltage	$V_{IN}$	3.3 to 24	V
Logic Supply	$V_{DD}$	4.5 to 5.5	
Input Logic PWM Voltage	$V_{PWM}$	5	
Bootstrap Capacitor	$C_{BOOT}$	100 n to 1 $\mu$	F

<b>THERMAL RESISTANCE RATINGS</b>					
Parameter <sup>c</sup>		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Case	Steady State	$R_{thJC}$	3.5	4.5	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Ambient (PCB = Copper 25 mm x 25 mm)		$R_{thJA}$	60	75	

## Notes:

- See Reliability Manual for profile. The PowerPAK MLF 9 x 9 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side soldering interconnection.
- Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Junction-to-case thermal impedance represents the effective thermal impedance of all heat carrying leads in parallel and is intended for use in conjunction with the thermal impedance of the PC board pads to ambient ( $R_{thJA} = R_{thJC} + R_{thPCB-A}$ ). It can also be used to estimate chip temperature if power dissipation and the lead temperature of heat carrying (drain) lead is known.

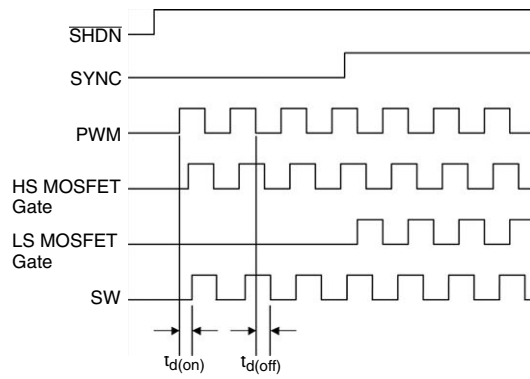


SPECIFICATIONS							
Parameter	Symbol	Test Conditions Unless Specified $T_A = 25\text{ }^\circ\text{C}$ $4.5\text{ V} < V_{DD} < 5.5\text{ V}, 4.5\text{ V} < V_{IN} < 20\text{ V}$		Limits			Unit
				Min	Typ <sup>a</sup>	Max	
<b>Controller</b>							
Logic Voltage	$V_{DD}$		4.5		5.5		V
Logic Current (Static)	$I_{DD(EN)}$	$V_{DD} = 4.5\text{ V}, \text{SYNC} = \text{H}, \text{PWM} = \text{H}, \overline{\text{SHDN}} = \text{H}$		1185			$\mu\text{A}$
	$I_{DD(DIS)}$	$V_{DD} = 4.5\text{ V}, \text{SYNC} = \text{H}, \text{PWM} = \text{H}, \overline{\text{SHDN}} = \text{L}$		115			
Logic Current (Dynamic)	$I_{DD1(DYN)}$	$V_{DD} = 5\text{ V}, f_{\text{PWM}} = 250\text{ kHz}^c$		24			mA
	$I_{DD2(DYN)}$	$V_{DD} = 5\text{ V}, f_{\text{PWM}} = 700\text{ kHz}^c$		52			
<b>Logic Input</b>							
Logic Input (VPWM)	High	$V_{\text{PVMH}}$	$V_{DD} = 5\text{ V}, \text{SYNC} = \text{H}, \overline{\text{SHDN}} = \text{H}$	2.5			V
	Low	$V_{\text{PVM L}}$				1.35	
Logic Input Voltage ( $V_{\text{SYNC}}$ )		$V_{\text{SYNC}}$	$V_{DD} = 5\text{ V}, \text{PMW} = \text{H}, \overline{\text{SHDN}} = \text{H}$		2.0		
Logic Input Voltage ( $V_{\text{SHDN}}$ )		$V_{\text{SHDN}}$	$V_{DD} = 5\text{ V}, \text{PMW} = \text{H}, \text{SYNC} = \text{H}$		2.0		
Input Voltage Hysteresis (PWM)		$V_{\text{HYS}}$			400		mV
Logic Input Current		$I_{\text{SHDN}}$	$V_{DD} = 5.5\text{ V}, \overline{\text{SHDN}} = 0\text{ V}$		117		$\mu\text{A}$
		$I_{\text{PWM}}$	$V_{DD} = 5.5\text{ V}, \text{PMW} = 5.5\text{ V}$		114		
<b>Protection</b>							
Break-Before-Make Reference		$V_{\text{BBM}}$	$V_{DD} = 5.5\text{ V}$		2.4		V
Under-Voltage Lockout		$V_{\text{UVLO}}$	$V_{DD} = 5\text{ V}, \text{SYNC} = \text{H}, \overline{\text{SHDN}} = \text{H}$	3.5	4.1	4.25	
Under-Voltage Lockout Hysteresis		$V_{\text{H}}$			0.4		
<b>MOSFETs</b>							
Drain-Source Voltage		$V_{\text{DS}}$	$I_D = 250\text{ }\mu\text{A}$	30	32		V
Drain-Source On-State Resistance <sup>a</sup>		$r_{\text{DS(on)1}}$	$V_{DD} = 5\text{ V}, I_D = 10\text{ A}$ $T_A = 25\text{ }^\circ\text{C}$	High-Side	9.5	12.3	m $\Omega$
		$r_{\text{DS(on)2}}$		Low-Side	3.7	4.5	
Diode Forward Voltage <sup>a</sup>		$V_{\text{SD1}}$	$I_S = 2\text{ A}, V_{\text{GS}} = 0\text{ V}$	High-Side	0.7	1.1	V
		$V_{\text{SD2}}$		Low-Side	0.67	1.1	
<b>Dynamic<sup>b, c</sup></b>							
Turn On Delay Time		$t_{\text{d(on)}}$	50 % - 50 % <sup>c</sup>		58		ns
Turn Off Delay Time		$t_{\text{d(off)}}$			31		

Notes:

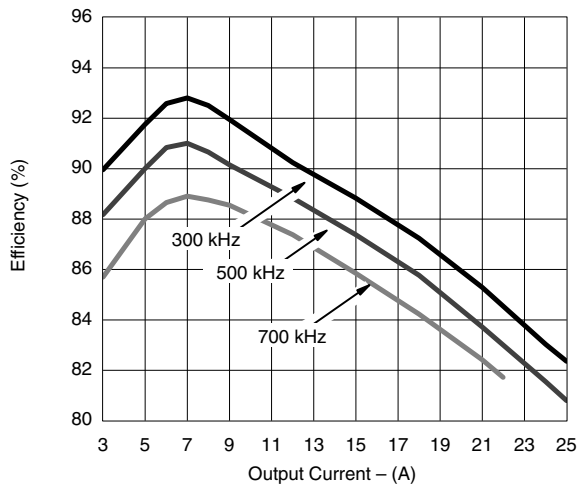
- a. Pulse test; pulse width  $\leq 300\text{ ms}$ , duty cycle  $\leq 2\%$ .
- b. Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.
- c. Using application board SiDB766706.

**TIMING DIAGRAM**

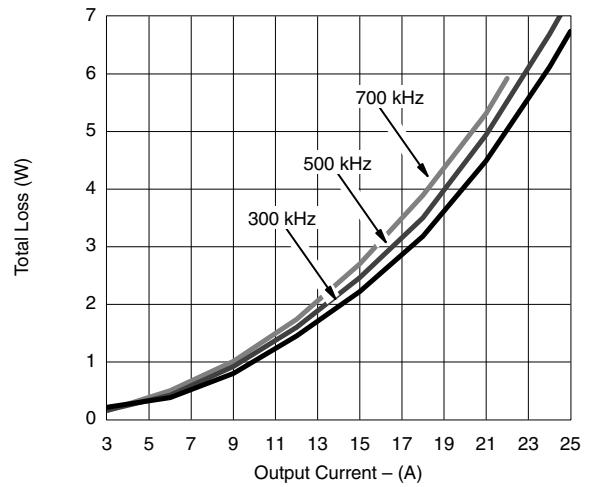


**Figure 2.**

**APPLICATION INFORMATION<sup>a</sup>** (25 °C, unless noted, LFM = 0)



**Figure 3. Total Efficiency 12 V<sub>IN</sub>/1.3 V<sub>OUT</sub>**



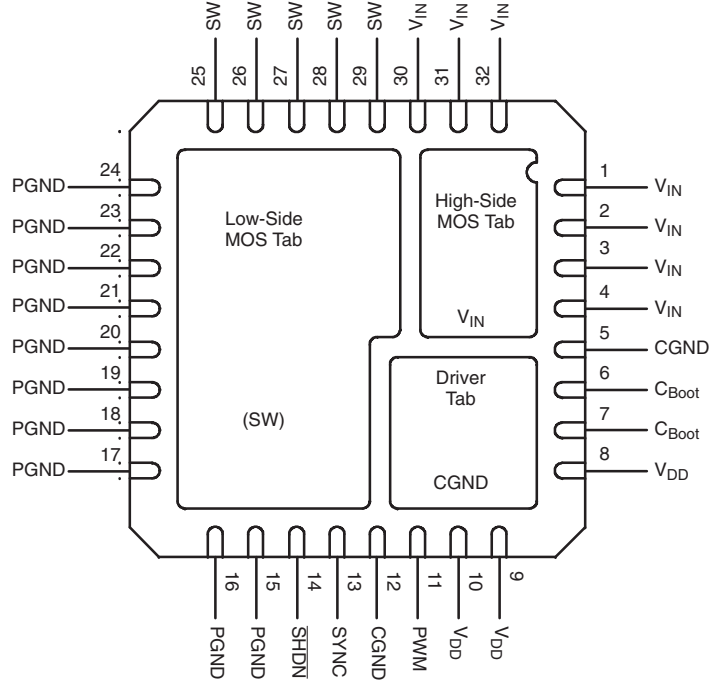
**Figure 4. Total Loss 12 V<sub>IN</sub>/1.3 V<sub>OUT</sub>**

Notes:

a. Experimental results using an evaluation board with a specific set of operating conditions.

**PIN CONFIGURATION**

PowerPAK MLF 9 mm x 9 mm (Bottom View)



TRUTH TABLE				
SHDN	SYNC	PWM	HS MOSFET	LS MOSFET
L	X	X	OFF	OFF
H	L	L	OFF	OFF
H	L	H	ON	OFF
H	H	L	OFF	ON
H	H	H	ON	OFF

PIN DESCRIPTION		
Pin Number	Symbol	Description
1 - 4, 30 - 32	$V_{IN}$	Input-Voltage (High-Side MOSFET Drain)
5, 12	CGND	Control Ground. Should be connected to PGND externally
6, 7	$C_{BOOT}$	Connection pin for Bootstrap Capacitor for High-Side MOSFET
8, 9, 10	$V_{DD}$	Logic Supply Voltage - decoupling to GND with a CAP is strongly recommended
11	PMW	Pulse Width Modulation (PWM) Signal Input
13	SYNC	Disable Low-Side MOSFET Drive
14	SHDN	Disable All Functions (Active Low)
15 - 24	PGND	Power Ground (Low-Side MOSFET Source)
25 - 29	SW	Connection Pin for Output Inductor (High-Side MOSFET Source/Low-Side MOSFET Drain)

**DEVICE OPERATION****Pulse Width Modulator (PWM)**

This is a CMOS compatible logic input that receives the drive signals from the controller circuit. The PWM signal drives the buck switch.

**Break-Before-Make (BBM)**

The SiC730CD9 has an internal break-before-make function to ensure that both high-side and low-side MOSFETs are not turned on at the same time. The low-side MOSFET will not turn on until the high-side gate drive voltage is less than  $V_{BBM}$ , thus ensuring that the high-side MOSFET is turned off. This parameter is not user adjustable.

**SHDN**

CMOS logic signal. In the low state, the  $\overline{\text{SHDN}}$  disables both high-side and low-side MOSFETs.

**Capacitor to Boot Input ( $C_{BOOT}$ )**

Connected to  $V_{DD}$  by an internal diode via the  $C_{BOOT}$  pin, the boot capacitor is used to sustain rail for the high-side MOSFET gate drive circuit.

**Under Voltage Lockout (UVLO)**

During the start up cycle, the UVLO disables the gate drive holding high-side and low-side MOSFETs low until the input voltage rail has reached a point at which the logic circuitry can be safely activated. The UVLO is not user adjustable.

**APPLICATION CIRCUIT**

**Power Up Sequence:** The presence of  $V_{DD}$  prior to applying the  $V_{IN}$  and PWM is recommended to ensure a safe turn on

**Power Down Sequence:** The sequence should be reverse of the on sequence, turn off the  $V_{IN}$  before turning off the  $V_{DD}$ .

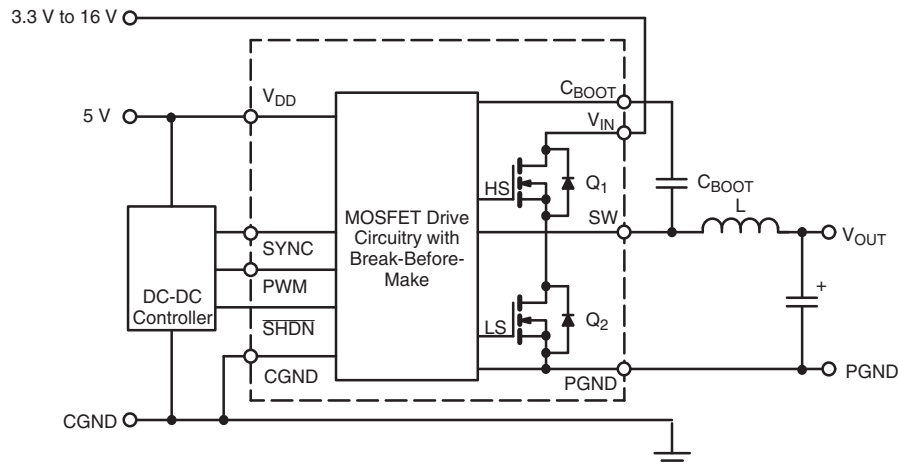


Figure 7

The SiC714CD10 has a built-in delay time that is optimized for the MOSFET pair. When the PWM signal goes low, the high-side driver will turn off, after circuit delay ( $t_{doff}$ ), and the output will start to ramp down, ( $t_f$ ). After a further delay, the low-side driver turns on.

The SiC734CD9 has a built-in delay time that is optimized for the MOSFET pair. When the PWM signal goes low, the high-side driver will turn off, after circuit delay ( $t_{doff}$ ), and the output will start to ramp down, ( $t_f$ ). After a further delay, the low-side driver turns on.

**SYNC Pin for Pre-Bias Start-Up**

The low side MOSFET can be individually enable or disabled by using the SYNC pin. In the low state (SYNC = low), the low-side MOSFET is turned off. In the high state, the low-side MOSFET is enabled and follows the PWM input signal (see timing diagram, Figure 2). SYNC is a CMOS compatible logic input and is used for a pre-biased output voltage.

**Voltage Input ( $V_{IN}$ )**

This is the power input to the drain of the high-side Power MOSFET. This pin is connected to the high power intermediate BUS rail.

**Switch Node (SW)**

The Switch node is the circuit PWM regulated output. This is the output applied to the filter circuit to deliver the regulated high output for the buck converter.

**Power Ground (PGND)**

This is the output connection from the source of the low-side MOSFET. This output is the ground return loop for the power rail. It should be externally connected to CGND.

**Control Ground (CGND)**

This is the control voltage return path for the driver and logic input circuitry to the SiC730CD9. This should externally connected to PGND.

When the PWM goes high, the low-side driver turns off, ( $t_{don}$ ). As the body diode starts to conduct, the high-side MOSFET turns on after a short delay. The delay is minimized to limit body diode conduction. The output then ramps up, ( $t_r$ ).

When the PWM goes high, the low-side driver turns off, ( $t_{don}$ ). As the body diode starts to conduct, the high-side MOSFET turns on after a short delay. The delay is minimized to limit body diode conduction. The output then ramps up, ( $t_r$ ).

**TYPICAL APPLICATION**

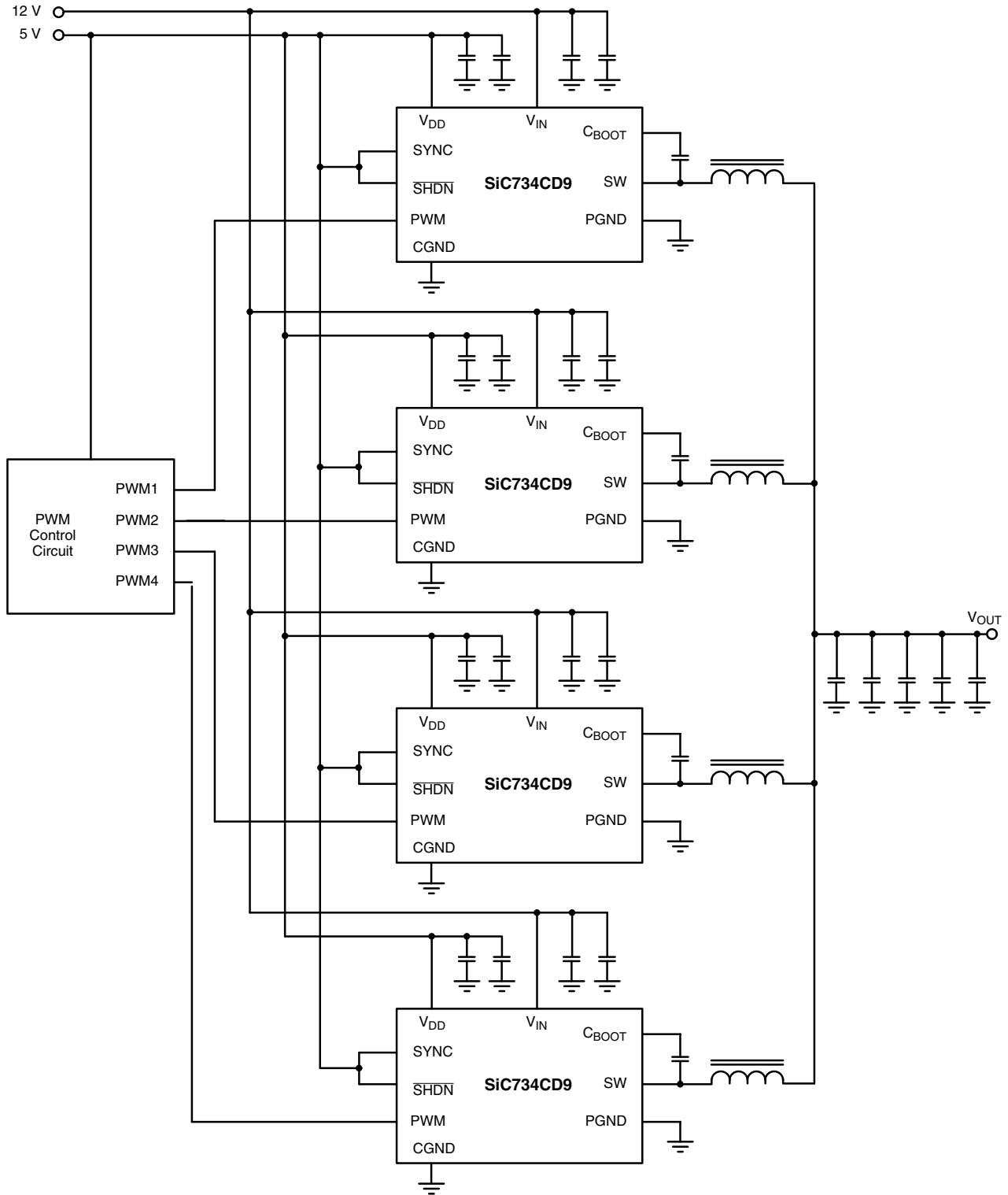
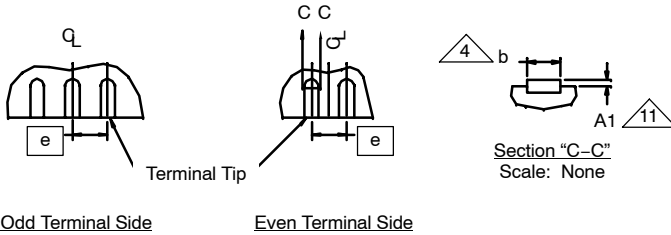
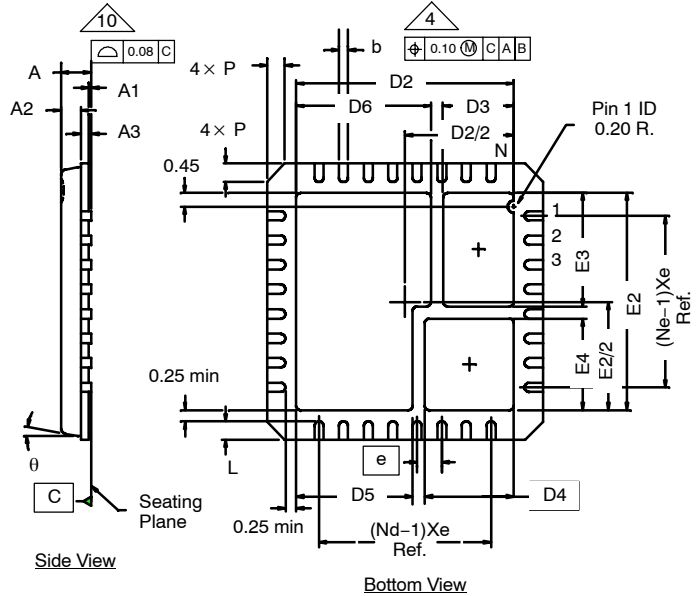
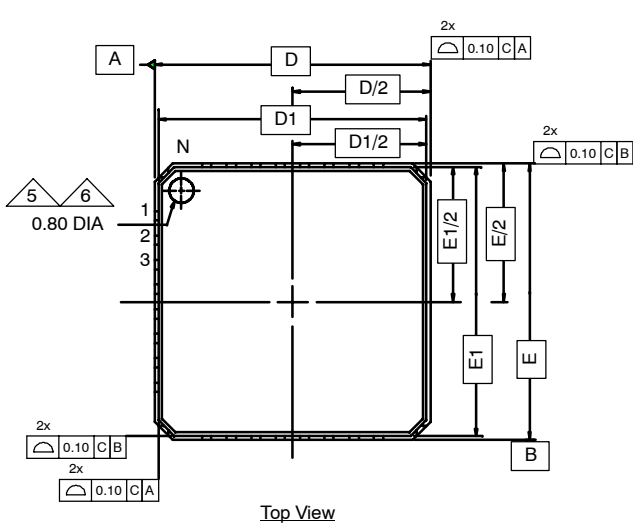


Figure 8.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <http://www.vishay.com/ppg?73672>.



PowerPAK® MLF 9 × 9



NOTES:

1. Die thickness allowable is 0.305-maximum (0.12-inches maximum)
2. Dimensioning and tolerancing conform to ASME Y14.5M-1994.
3. N is the total number of terminals. Nd is the number of terminals in the X-direction and Ne is the number of terminals in the Y-direction.

4. Dimension b applies to plated terminal and is measured between 0.20 mm and 0.25 mm from the terminal tip.
5. The pin #1 identifier must exist on the top surface of the package. The identifier may be an indentation mark or other feature of the package body.
6. Exact shape and size of this feature is optional.
7. Millimeters will govern.
8. The shape shown on four corners are not actual I/O.
9. Package warpage maximum is 0.08 mm.
10. Applied for exposed pad and terminals exclude embedding part of exposed pad from measuring.
11. Applied only for terminals.





### PowerPAK® MLF 9 × 9

EXPOSED PAD VARIATIONS (Millimeters)											
D2			E2			D3			E3		
Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
6.95	7.10	7.25	6.95	7.10	7.25	2.15	2.30	2.45	3.55	3.70	3.85
D4			E4			D5			D6		
Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
2.75	2.90	3.05	2.85	3.00	3.15	3.65	3.80	3.95	4.25	4.40	4.55
EXPOSED PAD VARIATIONS (Inches)											
D2			E2			D3			E3		
Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
0.274	0.280	0.285	0.274	0.280	0.285	0.085	0.091	0.096	0.140	0.146	0.152
D4			E4			D5			D6		
Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
0.108	0.114	0.120	0.112	0.118	0.124	0.144	0.150	0.155	0.167	0.173	0.179

DIMENSIONS							
Dim	MILLIMETERS*			INCHES			NOTE
	Min	Nom	Max	Min	Nom	Max	
A	—	0.85	0.90	—	0.033	0.035	
A1	0.00	0.01	0.05	0.000	—	0.002	11
A2	—	0.65	0.80	—	0.026	0.031	
A3	0.20 REF			0.008 REF			
b	0.25	0.30	0.35	0.010	0.012	0.014	4
D	9.00 BSC			0.354 BSC			
D1	8.75 BSC			0.344 BSC			
e	0.80 BSC			0.031 BSC			
E	9.00 BSC			0.354 BSC			
E1	8.75 BSC			0.344 BSC			
L	0.50	0.60	0.75	0.020	0.024	0.030	
N	32			32			3
Nd	8			8			3
Ne	8			8			3
P	0.24	0.42	0.60	0.009	0.017	0.024	
θ	—	—	12°	—	—	12°	

\* Use millimeters as the primary measurement.

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DWG: 5948



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